PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Reza A. Pagaila	06/19/2009
Byung Tai Do	06/19/2009
Shaungwu Huang	06/19/2009
Rajendra D. Pendse	07/09/2009

RECEIVING PARTY DATA

Name:	STATS ChipPAC, Ltd.
Street Address:	10 Ang Mo Kio Street 65
Internal Address:	#05-17/20 Techpoint
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	569059

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12492360

CH $40.00 12492360

CORRESPONDENCE DATA

Fax Number: (602)748-4414
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 602-748-4408
Email: main@plgaz.com
Correspondent Name: Robert D. Atkins
Address Line 1: 605 W. Knox Road
Address Line 2: Suite 104
Address Line 4: Tempe, ARIZONA 85284

ATTORNEY DOCKET NUMBER:	2515.0160
NAME OF SUBMITTER:	Robert D. Atkins

Total Attachments: 5
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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, REZA A. PAGAILA of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING VERTICAL INTERCONNECT STRUCTURE USING STUD BUMPS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0160, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

Signature for REZA A. PAGAILA

Witnessed on this date: 19 JUNE 2009

Signature of Witness:

Printed Name of Witness: DIOSCORO MERILO

Address of Witness: BLK. 966, HOUGANG AVE. 9
#10-592, SINGAPORE 530966

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, BYUNG TAI DO of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING VERTICAL INTERCONNECT STRUCTURE USING STUD BUMPS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0160, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

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I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

Signature for BYUNG TAI DO

Witnessed on this date: 19 JUNE 2009

Signature of Witness:

Printed Name of Witness: DIOSCORO MERILO

Address of Witness: BLK. 966, HOUGANG AVE. 9
#10-592, SINGAPORE 530966

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, SHUANGWU HUANG of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING VERTICAL INTERCONNECT STRUCTURE USING CONDUCTIVE PILLARS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0160, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

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I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

Huangwu

Signature for SHUANGWU HUANG

Witnessed on this date: 19 JUNE 2009

Signature of Witness:

Printed Name of Witness: DIOSCORO MERILO

Address of Witness: BLK. 966, HOUGANG AVE. 9
#10-592, SINGAPORE 530966

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I,RAJENDRA D. PENDSE of Fremont, California, have sold, assigned, and transferred, and do hereby sell, assign, and transfer untoSTATS ChipPAC Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitledSEMICONDUCTOR DEVICE AND METHOD OF FORMING VERTICAL INTERCONNECT STRUCTURE USING STUD BUMPS, which is described, illustrated, and claimed in United States Application No. 12/492,360, filed June 26, 2009, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s)

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which descibe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer untoSTATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the aboveidentified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in theUnited States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, toSTATS ChipPAC, for the sole use and behalf ofSTATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name ofSTATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge toSTATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto inSTATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

Signature for RAJENDRA D. PENDSE

~~STATE OF~~ CALIFORNIA)
COUNTY OF ______________)

I, ______________________________, a Notary Public in and for the County and State aforesaid, do hereby certify that RAJENDRA D. PENDSE~~, whose~~ name is subscribed to the foregoing instrument, appeared before me this day in person and acknowledged that he/~~she signed~~, sealed and delivered the instrument as his/her free and voluntary act and deed for the uses and purposes therein set ~~forth~~.

Given under my hand and notarial seal this______________ day of______________, 2009.

See Attached

____
Signature of Notary

CALIFORNIA ALL-PURPOSE ACKNOWLEDGMENT

State of California
County of Alameda

On July 9, 2009 (Date) before me, Jacqueline M. Curtis, Notary Public (Here Insert Name and Title of the Officer),
personally appeared Rajendra D. Pendse (Name(s) of Signer(s))

JACQUELINE M. CURTIS
Commission # 1657093
Notary Public - California
Alameda County
My Comm. Expires Apr 9, 2010

who proved to me on the basis of satisfactory evidence to be the person~~(s)~~ whose name~~(s)~~ is/~~are~~ subscribed to the within instrument and acknowledged to me that he/~~she/they~~ executed the same in his/~~her/their~~ authorized capacity~~(ies)~~, and that by his/~~her/their~~ signature~~(s)~~ on the instrument the person~~(s)~~, or the entity upon behalf of which the person~~(s)~~ acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.

Place Notary Seal Above

Signature ______ Signature of Notary Public

OPTIONAL

Though the information below is not required by law, it may prove valuable to persons relying on the document and could prevent fraudulent removal and reattachment of this form to another document.

Description of Attached Document

Title or Type of Document: Assignment & Agreement
Document Date: July 9, 2009 Number of Pages: 1
Signer(s) Other Than Named Above: N/A

Capacity(ies) Claimed by Signer(s)

Signer's Name: Rajendra D. Pendse
☑ Individual
☐ Corporate Officer — Title(s):
☐ Partner — ☐ Limited ☐ General
☐ Attorney in Fact
☐ Trustee
☐ Guardian or Conservator
☐ Other:
Signer Is Representing:

RIGHT THUMBPRINT OF SIGNER
Top of thumb here

Signer's Name:
☐ Individual
☐ Corporate Officer — Title(s):
☐ Partner — ☐ Limited ☐ General
☐ Attorney in Fact
☐ Trustee
☐ Guardian or Conservator
☐ Other:
Signer Is Representing:

RIGHT THUMBPRINT OF SIGNER
Top of thumb here